

PRODUCT NO.
73725

PRODUCT NUMBER CODE

73725-X X X X LF

HOUSING COLOR OPTION
0-WHITE
1-BLACK

SENSOR CONTACT OPTION
0-WITH SENSOR CONTACT
1-WITHOUT SENSOR CONTACT

SHIELD PLATING OPTION
1- 1.25μm MINIMUM NICKEL UNDERPLATE &
2.5μm MINIMUM BRIGHT TIN OVER ALL AREA.
(HOLD DOWN STYLE "A")
2- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL;
2.5 μm MINIMUM MATTE TIN PLATED ON
HOLD DOWN AREA ONLY.(HOLD DOWN STYLE "B")
3- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL;
2.5 μm MINIMUM MATTE TIN PLATED ON
HOLD DOWN AREA ONLY.(HOLD DOWN STYLE "A")
4- 1.25μm MINIMUM NICKEL UNDERPLATED &
2.5μm MINIMUM BRIGHT TIN OVER ALL AREA.
(HOLD DOWN STYLE "B")
5- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL;
2.5μm MINIMUM MATTE TIN PLATED ON
HOLD DOWN AREA ONLY (HOLD DOWN STYLE "C")
6- 1.25μm MINIMUM NICKEL ONLY.
(HOLD DOWN STYLE "A")
7- 1.25μm MINIMUM NICKEL UNDERPLATED &
2.5 μm MINIMUM MATTE TIN PLATED OVER ALL.
(HOLD DOWN STYLE "A")
8- 1.25μm MINIMUM NICKEL UNDERPLATED &
2.5 μm MINIMUM MATTE TIN PLATED ALL AREA.
(HOLD DOWN STYLE "B")
9- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL;
2.5 μm MINIMUM MATTE TIN PLATED ON
HOLD DOWN AREA ONLY (HOLD DOWN STYLE "D")
S- 1.25μm MINIMUM NICKEL ONLY.(HOLD DOWN STYLE "A").
HIGH PERFORMANCE MATERIAL
FOR 12,000 DURABILITY CYCLES
A- 1.25μm MINIMUM NICKEL PLATED OVER ALL
2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY
(HOLD DOWN STYLE "F")
B- 1.25μm MINIMUM NICKEL PLATED OVER ALL
2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY
(HOLD DOWN STYLE "F")

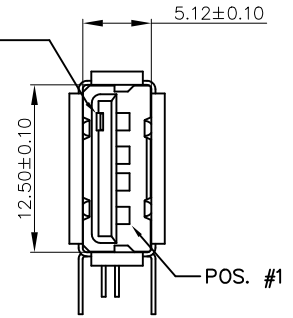
TERMINAL OPTION
50u" NI UNDERPLATE; 30u" GXT CONTACT AREA,100u" TIN TAIL AREA;
0- DIM "A": 2.29 (TERMINAL TAIL LENGTH);
1- DIM "A": 3.71 (TERMINAL TAIL LENGTH);

LEAD FREE OPTION
SEE NOTE 9

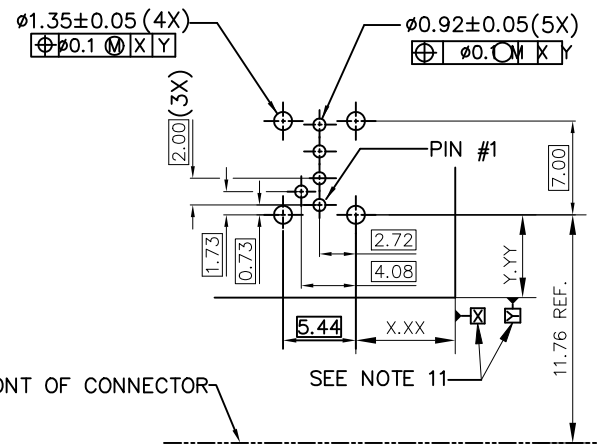
PACKAGING OPTION
B - TUBE
R - TAPE&REEL



SENSOR CONTACT

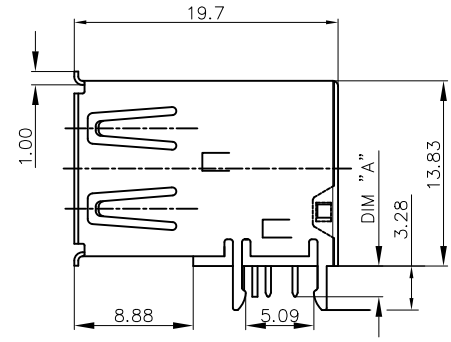


WITH SENSOR CONTACT



FRONT OF CONNECTOR

PC BOARD MOUNTING DIMENSIONS FOR 5 PIN



FOR 73725-X0X0B
HOLD DOWN STYLE "A"

NOTES:

- MATERIAL:
CONTACTS: COPPER ALLOY
SHIELD: COPPER ALLOY
HOUSING: UL 94V-0 THERMOPLASTIC, COLOR: SEE PRODUCT CODE
- PLATING:
CONTACTS: GOLD FLASH OVER PALLADIUM NICKEL (0.76μm MINIMUM)
IN CONTACT AREA; 2.5 μm TIN MINIMUM IN SOLDER TAIL AREA.
1.27 μm MINIMUM NICKEL UNDERPLATE OVER ALL SURFACES.
SHIELD: SEE PRODUCT NUMBER CODE.
(THE PLATING MEASURE POINT ON THE SHIELD HOLD DOWN AREA ONLY).
- DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER
- RECOMMENDED PCB BOARD THICKNESS IS 1.00 ~ 1.60mm EXCEPT 73725-1191BLF;
73725-1191BLF CAN BE USED FOR THE PCB BOARD THICKNESS 2.30 ~ 2.65mm.
- MAXIMUM PANEL THICKNESS TO BE 2.67mm IF MOUNTED BEHIND PANEL
- METAL SHELL SLIVER 0.20 MAX.
- NI PLATING DOES NOT COMPLY WITH THE USB STANDARDS
(TO BE CONTINUED)

mat'l. code				surface ¹²³ /tolerance		projection 	product family HPL 511 USB 2.0	
ltr	ecn no	dr	date	ISO 1302	ISO 406 ISO 1101		title	
AJ	ELX-N-27706	LZ	2017/08/15	tolerances unless otherwise specified			USB UP-RIGHT RECEPT	
				angles	linear			
AD	ELX-N-012006	A.ZH	06/25/2012	0°±2'	.00±.10	scale 1:1	dwg no sheet 1 of 4 73725 A3	
AE	ELX-N-13463	A.ZH	11/14/2012	dr	PAMP	5/20/97		
AF	ELX-N-14592	J.HAN	06/10/2013	engr	R Y LIU	5/20/97		
AG	ELX-N-21594	LQ	08/04/2015	chr	R Y LIU	5/20/97		
AH	ELX-N-21919	LQ	08/04/2015	appd	JENN TSAO	5/20/97	type Product Customer Drawing	
sheet	revision							
index	sheet							

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(CONTINUED)

8. P/N'S WITH SUFFIX "LF" ARE LEAD FREE P/N'S

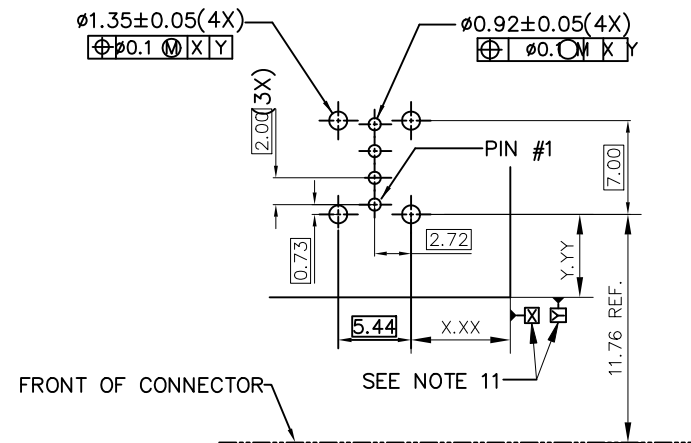
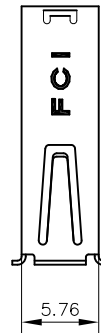
FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008

FOR THE PRODUCTS WITH THE METAL SHELL PLATING NICKEL AND MATTE SN CAN WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW PROCESS; FOR THE PRODUCTS WITH METAL SHELL PLATING BRIGHT SN OR SEMI-BRIGHT SN CAN'T WITHSTAND REFLOW AND JUST CAN WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN WAVE SOLDERING PROCESS.

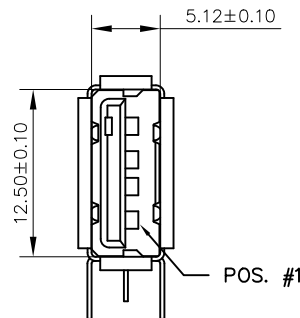
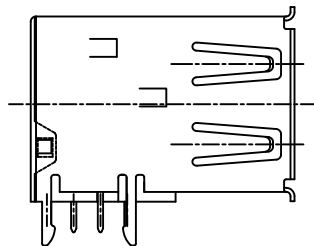
FOR ALL LEAD FREE P/N'S, WITH SUFFIX LF.

12. THE PRODUCT CAN BE USED FOR PIP PROCESS

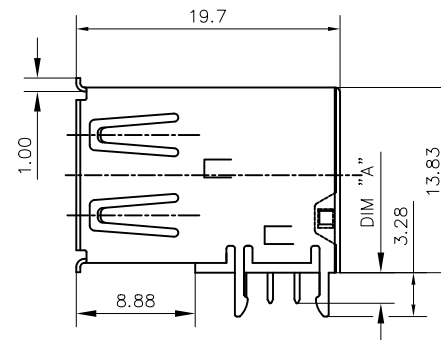
13. DATUM OF CUSTOMER'S PCB LAYOUT.



PC BOARD MOUNTING DIMENSIONS FOR 4 PIN

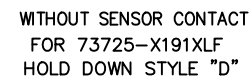
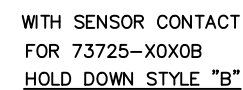
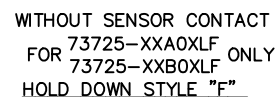
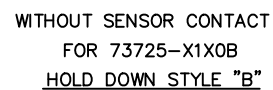


WITHOUT SENSOR CONTACT



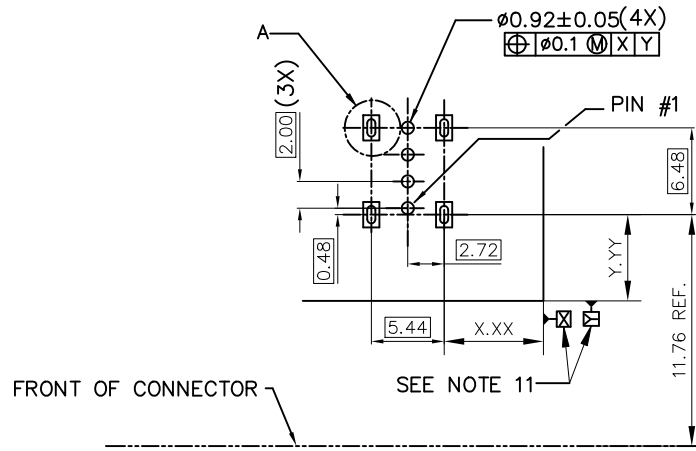
FOR 73725-X1X0B
HOLD DOWN STYLE "A"

mat'l. code				surface ¹²³ /tolerance			projection		product family		
				ISO 1302 ✓			ISO 406 ISO 1101		HPL 511 USB 2.0		
ltr		ecn no		dr		date		tolerances unless otherwise specified		title	
AJ								angles		USB UP-RIGHT	
								linear		RECEPT	
										mm	
								0°±2'		scale 1:1	
								dr		dwg no	
								PAMP		sheet2 of 4	
								eng		size	
								R Y LIU		5/20/97	
								chr		73725	
								R Y LIU		A3	
								5/20/97			
								appd		type	
								JENN TSAO		Product Customer Drawing	
								5/20/97			
sheet		revision									
index		sheet									

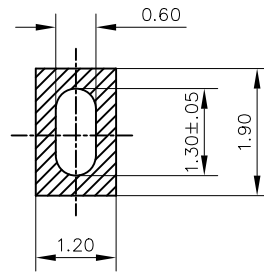


mat'l. code				surface ¹²³ /tolerance		projection		product family						
				ISO 1302 ✓ ISO 406 ISO 1101				HPL 511 USB 2.0						
ltr	ecn no	dr	date	tolerances unless otherwise specified				title						
AJ				angles		mm		USB UP-RIGHT RECEPT						
				linear										
				0°±2'		scale 1:1								
				.0±.30										
				.00±.20				dwg no						
				.000±.10										
				dr PAMP		5/20/97						sheet3 of 4		size
				eng R Y LIU		5/20/97						73725		A3
				chr R Y LIU		5/20/97		type Product Customer Drawing						
				app JENN TSAO		5/20/97								
sheet index		revision sheet												

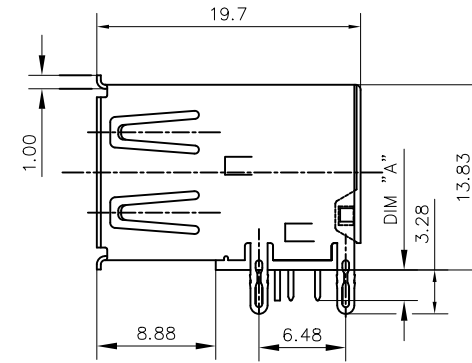
PRODUCT NO.
73725



PC BOARD MOUNTING DIMENSIONS FOR 4 PIN



DETAIL A 5 : 1



WITHOUT SENSOR CONTACT
FOR 73725-X150B
HOLD DOWN STYLE "C"

mat'l. code				surface ¹²³ /tolerance			projection 11011	product family			
				ISO 1302	ISO 406	ISO 11011		HPL 511 USB 2.0			
ltr	ecn no	dr	date	tolerances unless otherwise specified			mm	title			
AJ				angles	linear			USB UP-RIGHT RECEPT			
				0°±2°			scale 1:1				
				dr	PAMP	5/20/97	Amphenol FCI	dwg no		sheet 4 of 4	size
				engr	R Y LIU	5/20/97		73725			A3
				chr	R Y LIU	5/20/97					
				appd	JENN TSAO	5/20/97		type Product Customer Drawing			
sheet index		revision sheet									

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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